

SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

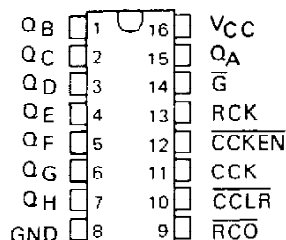
SDLS003

D2632, JANUARY 1981 — REVISED MARCH 1988

- 8-Bit Counter with Register
- Parallel Register Outputs
- Choice of 3-State ('LS590) or Open-Collector ('LS591) Register Outputs
- Guaranteed Counter Frequency: DC to 20 MHz

SN54LS590, SN54LS591 . . . J OR W PACKAGE
SN74LS590, SN74LS591 . . . N PACKAGE

(TOP VIEW)



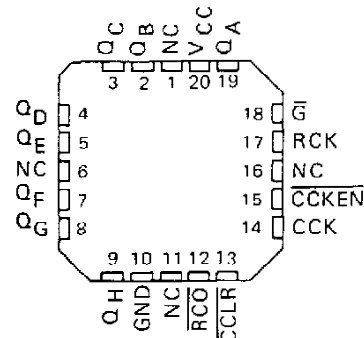
description

These devices each contain an 8-bit binary counter that feeds an 8-bit storage register. The storage register has parallel outputs. Separate clocks are provided for both the binary counter and storage register. The binary counter features a direct clear input $\overline{\text{CCLR}}$ and a count enable input $\overline{\text{CCKEN}}$. For cascading, a ripple carry output $\overline{\text{RCO}}$ is provided. Expansion is easily accomplished for two stages by connecting $\overline{\text{RCO}}$ of the first stage to $\overline{\text{CCKEN}}$ of the second stage. Cascading for larger count chains can be accomplished by connecting $\overline{\text{RCO}}$ of each stage to CCK of the following stage.

Both the counter and register clocks are positive-edge triggered. If the user wishes to connect both clocks together, the counter state will always be one count ahead of the register. Internal circuitry prevents clocking from the clock enable.

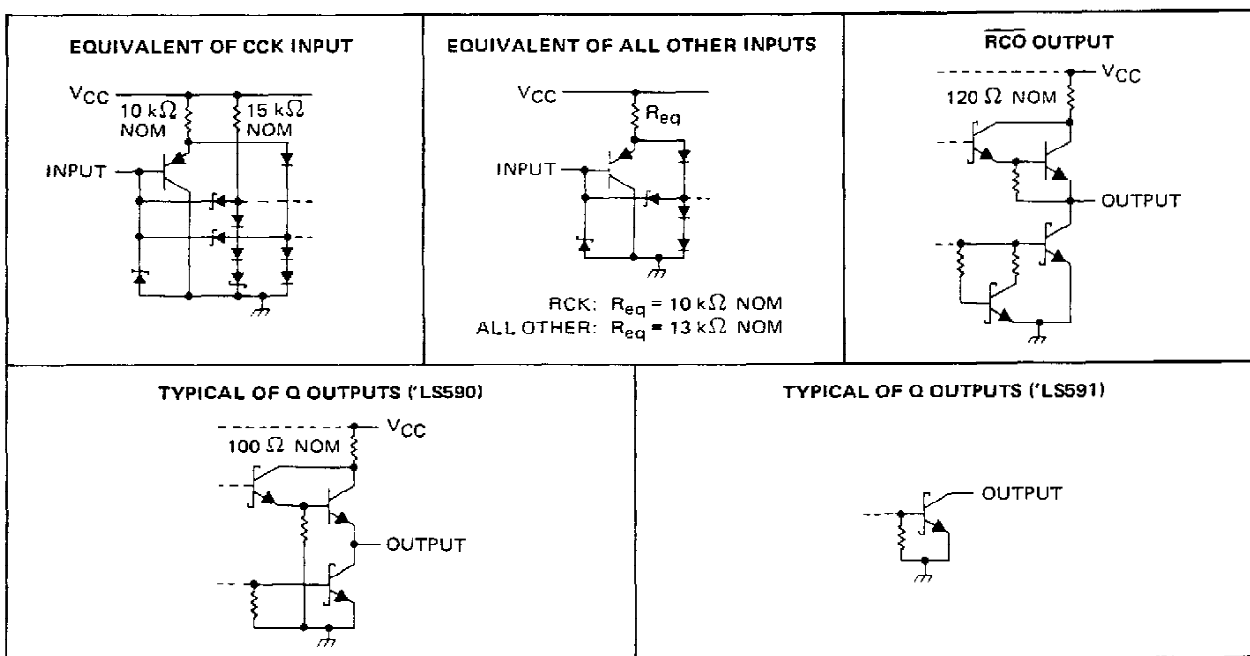
SN54LS590, SN54LS591 . . . FK PACKAGE

(TOP VIEW)



schematics of inputs and outputs

NC - No internal connection



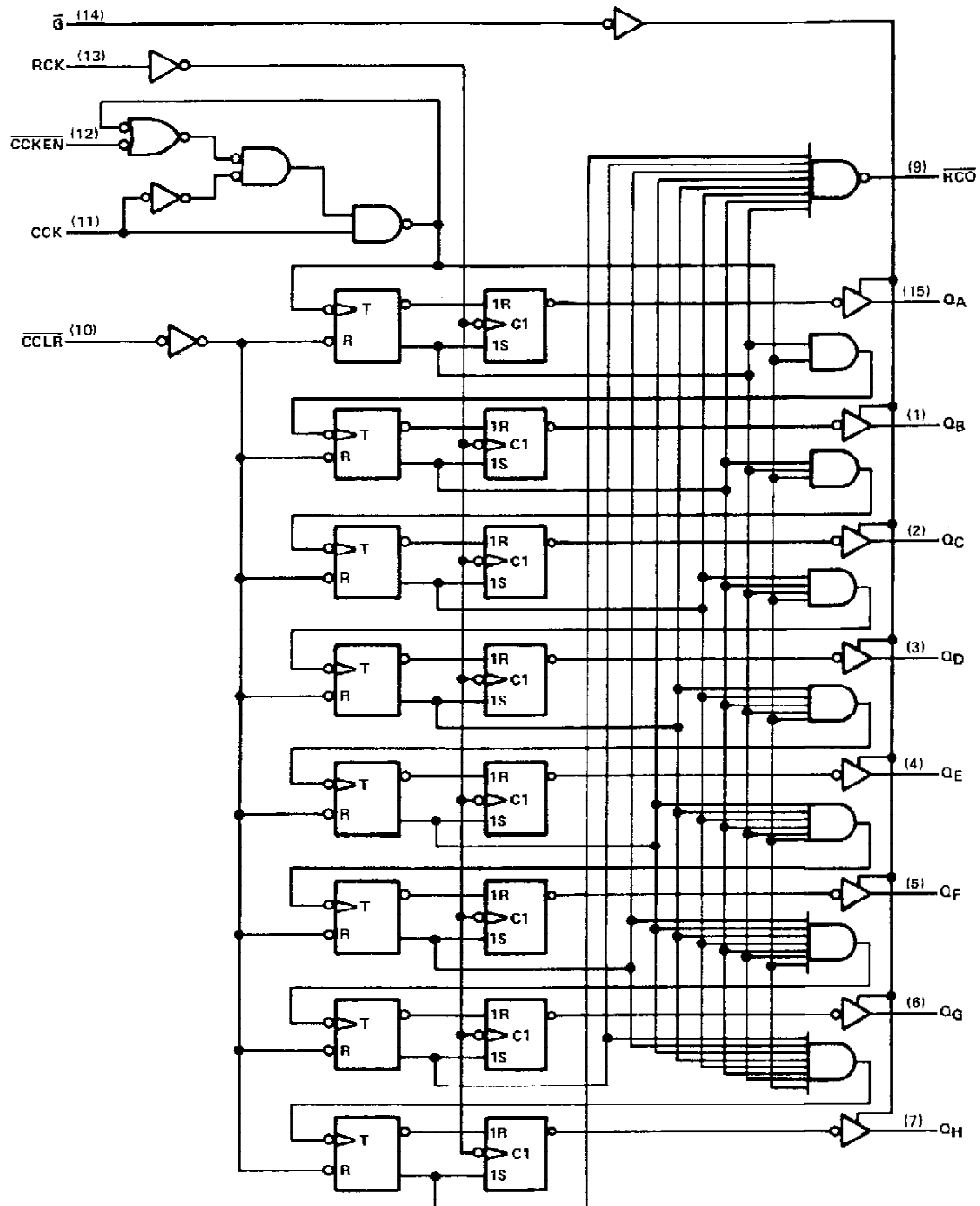
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS590, SN54LS591, SN74LS590, SN74LS591
8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

logic diagram (positive logic)



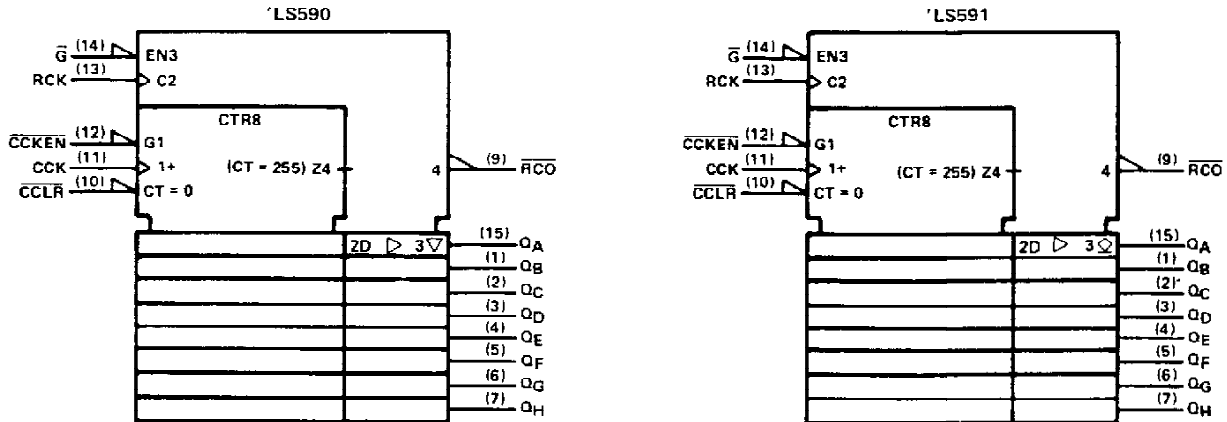
Pin numbers shown are for J, N and W packages.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS590, SN54LS591, SN74LS590, SN74LS591 8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

logic symbols†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS590, SN54LS591	-55°C to 125°C
SN74LS590, SN74LS591	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

		SN54LS*			SN74LS*			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
V_{OH}	High-level output voltage	Q, *LS591 only		5.5	5.5			V
I_{OH}	High-level output current	RCO		-1	-1			mA
		Q, *LS590 only		-1	-2.6			
I_{OL}	Low-level output current	RCO		8	16			mA
		Q		12	24			
f_{CCK}	Counter clock frequency	0		20	0		20	MHz
f_{RCK}	Register clock frequency	0		25	0		25	MHz
$t_w(CCK)$	Duration of counter clock pulse	25			25			ns
$t_w(CCLR)$	Duration of counter clear pulse	20			20			ns
$t_w(RCK)$	Duration of register clock pulse	20			20			ns
t_{su}	Setup time	CCKEN low before CCK ↑		20	20			ns
		CCLR inactive before CCK ↑		20	20			
		CCK before RCK ↑ (see Note 2)		40	40			
t_h	Hold time	CCKEN low after CCK ↑		0	0			ns
T_A	Operating free-air temperature	-55		125	0		70	$^{\circ}\text{C}$

NOTE 2: This setup time ensures the register will see stable data from the counter outputs. The clocks may be tied together in which case the register state will be one clock pulse behind the counter.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

SN54LS590, SN54LS591, SN74LS590, SN74LS591

8-BIT BINARY COUNTERS WITH OUTPUT REGISTERS

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS*		SN74LS*		UNIT		
					MIN	TYP‡	MAX	MIN		TYP‡	MAX
V _{IK}			V _{CC} = MIN,	I _I = - 18 mA		- 1.5		- 1.5	V		
V _{OH}	'LS590 Q	V _{CC} = MIN, V _{IL} = MAX	V _{IH} = 2 V,	I _{OH} = - 1 mA	2.4	3.2			V		
	I _{OH} = - 2.6 mA					2.4	3.1				
	I _{OH} = - 1 mA			2.4	3.2	2.4	3.2				
I _{OH}	'LS591 Q	V _{CC} = MIN, V _{IL} = MAX	V _{IH} = 2 V, V _{OH} = 5.5 V,			0.1		0.1	mA		
V _{OL}	Q	V _{CC} = MIN, V _{IL} = MAX	V _{IH} = 2 V,	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
	I _{OL} = 24 mA						0.35	0.5			
	RCO			I _{OL} = 8 mA		0.25	0.4		0.25	0.4	
				I _{OL} = 16 mA				0.35	0.5		
I _{OZH}	'LS590 Q	V _{CC} = MAX, V _O = 2.7 V	V _{IH} = 2 V, V _{IL} = MAX,			20		20	μA		
I _{OZL}	'LS590 Q	V _{CC} = MAX, V _O = 0.4 V	V _{IH} = 2 V, V _{IL} = MAX,			- 20		- 20	μA		
I _I			V _{CC} = MAX,	V _I = 7 V		0.1		0.1	mA		
I _{IH}			V _{CC} = MAX,	V _I = 2.7 V		20		20	μA		
I _{IL}	CCK	V _{CC} = MAX, V _I = 0.4 V				- 0.8		- 0.8	mA		
	All others					- 0.2		- 0.2			
I _{OS} §	'LS590 Q	V _{CC} = MAX, V _O = 0 V			- 30	- 130	- 30	- 130	mA		
	RCO				- 20	- 100	- 20	- 100			
I _{CC}	'LS590	V _{CC} = MAX, All possible inputs grounded, All outputs open	I _{CCH}		33	55		33 55	mA		
			I _{CCL}		44	65		44 65			
			I _{CCZ}		46	65		46 65			
	'LS591		I _{CCH}		35	55		35 55			
			I _{CCL}		42	65		42 65			

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V.}, T_A = 25^\circ\text{C}$

§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 \text{ V.}, T_A = 25^\circ\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS590			'LS591			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	RCK	Q	$R_L = 667 \Omega, C_L = 45 \text{ pF}$	20	35		20	35		MHz
t_{PLH}	CCK†	RCO	$R_L = 1 \text{ k}\Omega, C_L = 30 \text{ pF}$		14	22		16	24	ns
t_{PHL}	CCK†	RCO			20	30		25	38	ns
t_{PLH}	CCLR†	RCO			30	45		32	48	ns
t_{PLH}	RCK†	Q	$R_L = 667 \Omega, C_L = 45 \text{ pF}$		12	18		25	38	ns
t_{PHL}	RCK†	Q			22	33		28	42	ns
t_{PZH}	\bar{G}_1	Q			25	38				ns
t_{PZL}	\bar{G}_1	Q			30	45				ns
t_{PHZ}	\bar{G}_1	Q	$R_L = 667 \Omega, C_L = 5 \text{ pF}$		20	30				ns
t_{PLZ}	\bar{G}_1	Q			25	38				ns
t_{PLH}	\bar{G}_1	Q	$R_L = 667 \Omega, C_L = 45 \text{ pF}$					34	50	ns
t_{PHL}	\bar{G}_1	Q						32	48	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87517012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8751701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8751701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8751701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8751701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS590D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS590N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS590NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS590W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS590W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

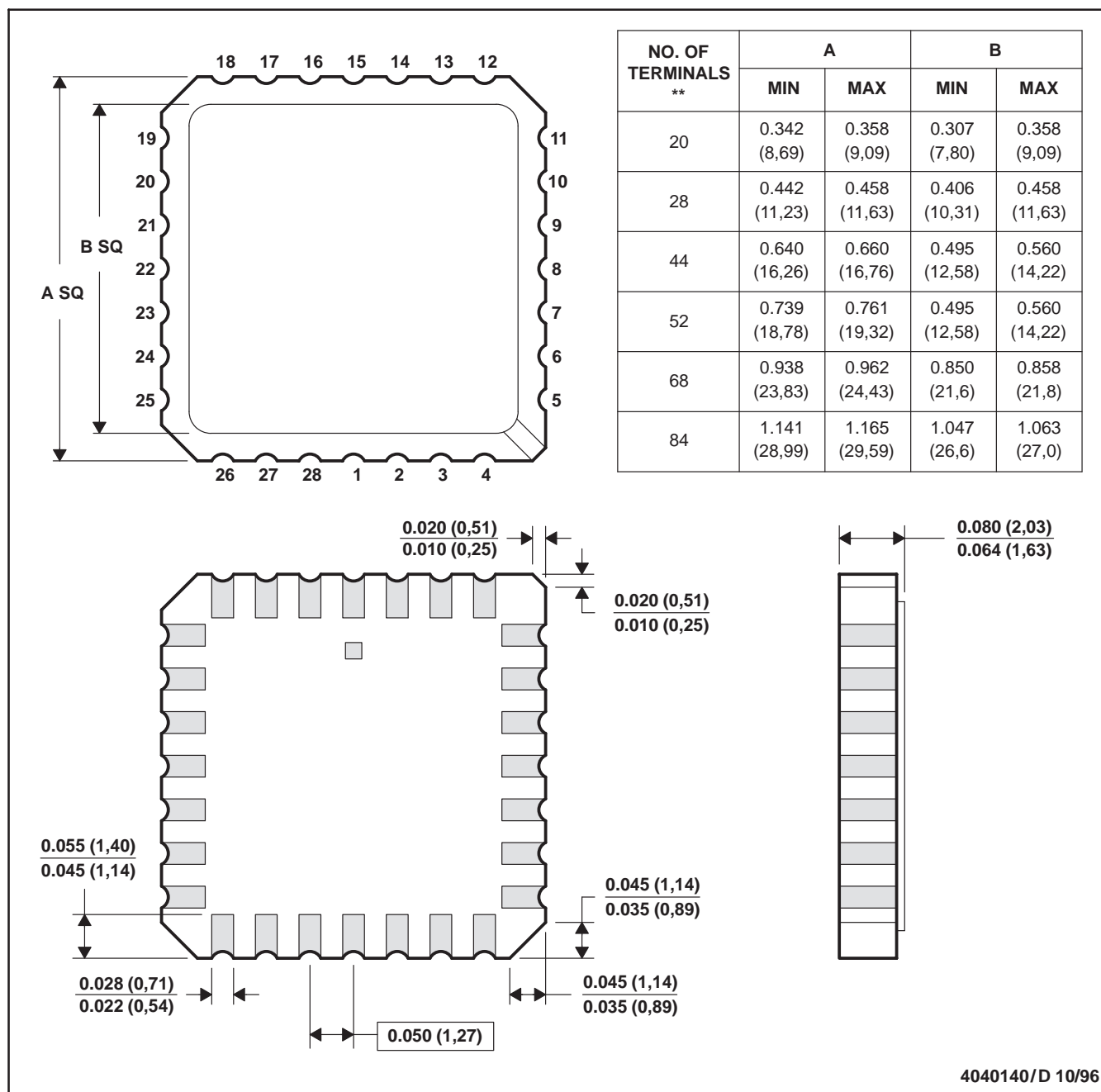


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
Low Power Wireless	www.ti.com/lpw

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87517012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8751701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8751701EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8751701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8751701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS590D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS590N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS590NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS590NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS590NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS590FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS590J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS590W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS590W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-4/H 11/2006

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
Low Power Wireless	www.ti.com/lpw

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265